# onsemi

# Automotive Gate Driver IC, High and Low Side 600 V, 4.5 A FAN7191-F085, FAD7191

#### Description

The FAN7191 / FAD7191 is a monolithic high– and low–side gate–driver IC, which can drive high speed MOSFETs and IGBTs that operate up to +600 V. It has a buffered output stage with all NMOS transistors designed for high pulse driving capability and minimum cross–conduction.

ON Semiconductor's high-voltage process and common-mode noise canceling technique provide stable operation of high-drivers under high dV/dt noise circumstances. An advanced level-shift circuit allows high-side gate driver operation up to  $V_S = -9.8$  V (typical) for  $V_{BS} = 15$  V.

The UVLO circuit prevents malfunction when  $V_{DD}$  and  $V_{BS}$  are lower than the specified threshold voltage.

The high current and low output voltage drop features make this device suitable for controlling direct injection actuators and for use in many automotive DC–DC converter and motor control applications.

#### Features

- Floating Channel for Bootstrap Operation to +600 V
- 4.5 A Sourcing and 4.5 A Sinking Current Driving Capability
- Common-Mode dV/dt Noise Cancelling Circuit
- Built-in Under-Voltage Lockout for Both Channels
- Matched Propagation Delay for Both Channels
- 3.3 V and 5 V Input Logic Compatible
- Output In-phase with Input
- Enable Pin (For 14–SOP Package Only)
- 14–SOP with Separate Signal and Power Ground for Enhanced Noise Immunity
- 14–SOP with Increased Clearance for High Voltage Applications
- Automotive Applications, AEC Qualified and PPAP Capable
- These Devices are Pb-Free and are RoHS Compliant

#### Applications

- Electric and Hybrid Electric Vehicles
- 48 V Mild Hybrid Vehicles
- Automotive High Voltage DC-DC converters
- Motor Control (Fans, Pumps, Compressors)
- Advanced Fuel Injection Systems
- Starter/Alternator
- Electric Power Steering
- MOSFET and IGBT Driver Applications



#### **ORDERING INFORMATION**

Part Number	Package	Shipping <sup>†</sup>
FAN7191MX-F085	8-SOP (751EB)	
FAN7191MX-F085-1	8-SOP (751EB)	2500 / Tape & Reel
FAD7191M1X	14-SOP (751EF)	

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

1

# **Typical Application Circuit**

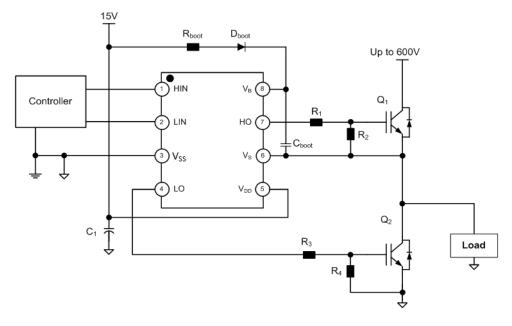
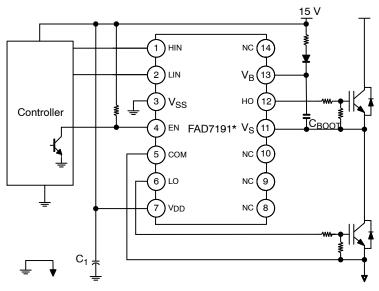


Figure 1. Half-Bridge Application Circuit (8-SOP)





### INTERNAL BLOCK DIAGRAM

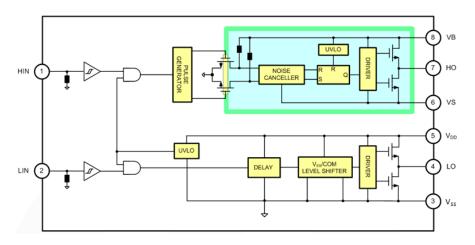


Figure 3. Functional Block Diagram (8-SOP)

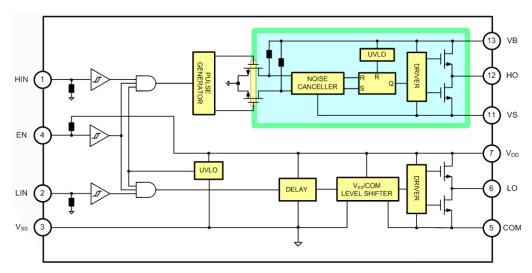


Figure 4. Functional Block Diagram (14–SOP)

## Pin Assignment

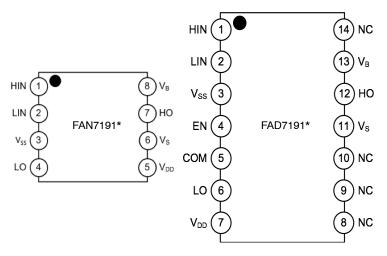


Figure 5. Pin Assignments (Top View)

#### Table 1. PIN DEFINITIONS

8–Pin	14–Pin	Name	Description
1	1	HIN	Logic Input for High-Side Gate Driver Output
2	2	LIN	Logic Input for Low-Side Gate Driver Output
3	3	V <sub>SS</sub>	Logic Ground, Power ground for 8–SOP
	4	EN	Enable Input (Internal Pull Up)
	5	СОМ	Power Ground for 14–SOP, Low–side Driver Return
4	6	LO	Low-Side Driver Output
5	7	V <sub>DD</sub>	Low-Side and Logic Power Supply Voltage
6	11	V <sub>S</sub>	High-Side Floating Supply Return
7	12	НО	High-Side Driver Output
8	13	VB	High-Side Floating Supply
	8, 9, 10, 14	NC	No Connect

#### **Table 2. ABSOLUTE MAXIMUM RATINGS**

(T<sub>A</sub> = -40°C to 125°C, unless otherwise specified. V<sub>B</sub>, V<sub>DD</sub> and V<sub>IN</sub> are referenced to V<sub>SS</sub>)

Symbol		Parameter		Min.	Max.	Unit
Vs	High-side offset voltag	ge VS		V <sub>B</sub> – 25	V <sub>B</sub> + 0.3	V
V <sub>B</sub>	High-side floating sup	ply voltage VB		-0.3	625	V
V <sub>HO</sub>	High-side floating out	put voltage		V <sub>S</sub> – 0.3	V <sub>B</sub> + 0.3	V
V <sub>DD</sub>	Low-side and logic-fi	xed supply voltage		-0.3	25	V
COM	Power Ground (14–S0	OP)		V <sub>DD</sub> – 25	V <sub>DD</sub> + 0.3	V
V <sub>IN</sub>	Logic Input voltage (H	IN, LIN, EN)		-0.3	V <sub>DD</sub> + 0.3	V
V <sub>LO</sub>	Low-Side Output Volt	Low-Side Output Voltage LO (8-SOP)		V <sub>SS</sub> – 0.3	V <sub>DD</sub> + 0.3	V
	Low-Side Output Voltage LO (14-SOP)		COM - 0.3	V <sub>DD</sub> + 0.3	V	
T <sub>pulse</sub> (Note 4)	Minimum Pulse Width		80		ns	
d <sub>VS/dt</sub>	Allowable offset voltage	Allowable offset voltage slew rate			50	V/ns
P <sub>D</sub>	Power Dissipation, T <sub>A</sub>	= 25°C	8-SOP		0.625	W
(Note 1, 2, 3)					0.80	W
$\theta_{JA}$	Thermal Resistance, j	unction-to-ambient	8-SOP		200	°C/W
(Note 1, 2)			14-SOP		156	°C/W
TJ	Junction temperature				+150	°C
Τ <sub>S</sub>	Storage temperature		-55	+150	°C	
ESD	Electrostatic	Human Body Model,	8-SOP		2500	V
	Discharge Capability	JESD22-A114	14-SOP		2000	
		Charged Device Model, JESD22-C101			2000	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Mounted on 76.2  $\times$  114.3  $\times$  1.6 mm PCB (FR-4 glass epoxy material).

2. Refer to the following standards: JESD51-2: Integral circuits thermal test method environmental conditions - natural convection.

JESD51-3: Low effective thermal conductivity test board for leaded surface mount packages.

3. P<sub>D</sub> is the power that raises T<sub>J</sub> to  $150^{\circ}$ C for T<sub>A</sub> =  $25^{\circ}$ C. P<sub>D</sub> to be derated at higher ambient temperature. 4. Minimum input pulse width that guarantee to produce an output pulse. Valid for turn on and turn off pulse width.

#### Table 3. RECOMMENDED OPERATING CONDITIONS (V<sub>S</sub>, V<sub>DD</sub> and V<sub>IN</sub> are referenced to V<sub>SS</sub>)

Symbol	Parameter	Min.	Max.	Unit
V <sub>B</sub>	High-side floating supply voltage	V <sub>S</sub> + 10	V <sub>S</sub> + 22	V
V <sub>S</sub>	High-side Floating Supply Offset Voltage	6 – V <sub>BS</sub>	600	V
V <sub>HO</sub>	High-side Output Voltage	V <sub>S</sub>	V <sub>B</sub>	V
V <sub>DD</sub>	Low-side and Logic Supply voltage	10	22	V
N/	Low-side output voltage (8-SOP)	0	V <sub>DD</sub>	V
V <sub>LO</sub>	Low-side output voltage (14-SOP)	СОМ	V <sub>DD</sub>	V
V <sub>IN</sub>	Logic input voltage (HIN, LIN, EN)	0	V <sub>DD</sub>	V
СОМ	Power Ground (14–SOP)	V <sub>DD</sub> – 22	V <sub>DD</sub>	V
T <sub>A</sub>	Ambient Temperature	-40	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### **Table 4. ELECTRICAL CHARACTERISTICS**

 $(V_{BIAS} (V_{DD}, V_{BS}) = 15.0 \text{ V}, V_S = V_{SS} = COM, T_A = -40^{\circ}C$  to 125°C, unless otherwise specified. The  $V_{IL}$ ,  $V_{IH}$  and  $I_{IN}$  parameters are referenced to V<sub>SS</sub> and are applicable to the respective input signals HIN and LIN. The V<sub>O</sub> and I<sub>O</sub> parameters are referenced to COM (or V<sub>SS</sub> in case of 8–SOP). V<sub>S</sub> and COM (V<sub>SS</sub> for 8–SOP) are applicable to the respective outputs HO and LO)

Symbol	Characteristic	Condition	Min.	Тур.	Max.	Unit
OWER SUPPLY	SECTION (V <sub>DD</sub> AND V <sub>BS</sub> )				•	•
V <sub>DDUV+</sub> V <sub>BSUV+</sub>	V <sub>DD</sub> and V <sub>BS</sub> Supply Under-Voltage Positive-going Threshold		7.8	8.8	9.8	V
V <sub>DDUV-</sub> V <sub>BSUV-</sub>	V <sub>DD</sub> and V <sub>BS</sub> Supply Under-Voltage Negative Going Threshold		7.2	8.3	9.1	
V <sub>DDHYS</sub>	V <sub>DD</sub> supply under-voltage lockout hysteresis			0.5		
I <sub>LK</sub>	Offset Supply Leakage Current	$V_{B} = V_{S} = 600 V$			50	μA
I <sub>QBS</sub>	Quiescent V <sub>BS</sub> Supply Current	$V_{IN} = 0 V \text{ or } 5 V$		45	110	
I <sub>QDD</sub>	Quiescent V <sub>DD</sub> Supply Current	$V_{IN} = 0 V \text{ or } 5 V$		75	150	
I <sub>PBS</sub>	Operating V <sub>BS</sub> Supply Current	f <sub>IN</sub> = 20 kHz, RMS value (See Figure 26)		400	800	μΑ
I <sub>PDD</sub>	Operating V <sub>DD</sub> Supply Current	f <sub>IN</sub> = 20 kHz, RMS value (See Figure 26)		400	800	
OGIC INPUT SE	CTION (HIN, LIN, EN)			•		•
V <sub>IH</sub>	Logic "1" Input Voltage		2.5			V
VIL	Logic "0" Input Voltage				1.2	1
I <sub>IN+</sub>	Logic "1" Input Bias Current (HIN/LIN)	V <sub>IN</sub> = 5 V		25	50	μΑ
I <sub>IN-</sub>	Logic "0" Input Bias Current (HIN/LIN)	V <sub>IN</sub> = 0 V		1.0	2.0	1

-114=	209:0 0pat 2:00 0 00			
I <sub>EN+</sub>	Enable High Input Bias Current	EN = 5 V	-100	-50
I <sub>EN-</sub>	Enable Low Input Bias Current	EN = 0 V	-140	-75
R <sub>IN</sub>	Input Pull-down Resistance		100	200

GATE DRIVER OUTPUT SECTION (HO, LO)

V <sub>OH</sub>	High-level Output Voltage, V <sub>BIAS</sub> -V <sub>O</sub>	No Load			1.35	V
V <sub>OL</sub>	Low-level Output Voltage, V <sub>O</sub>	No Load			35	mV
I <sub>O+</sub> (Note 5)	Output HIGH, Short-circuit Pulsed Current	$V_{O}$ = 0 V, $V_{IN}$ = 5 V with PW < 10 $\mu$ s	3.5	4.5		A
I <sub>O</sub> (Note 5)	Output LOW Short-circuit Pulsed Current	$V_O$ = 15 V, $V_{IN}$ = 0 V with $PW <$ 10 $\mu s$	3.5	4.5		
VS	Allowable Negative $V_S$ Pin Voltage for HIN Signal Propagation to HO	V <sub>BS</sub> = 15V		-9.8	-9.0	V
COM-V <sub>SS</sub> (Note 5)	Allowable COM-V <sub>SS</sub> ground offset	14–SOP, V <sub>DD</sub> = 15 V, V <sub>SS</sub> = 0 V	-7.0			V

-10 -20

kΩ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

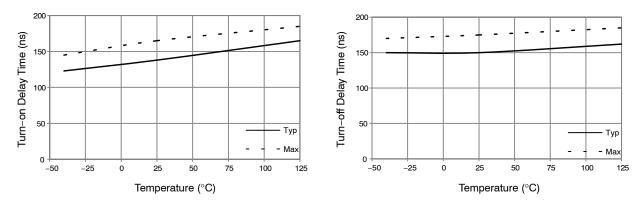
5. Parameters guaranteed by design.

#### Table 5. DYNAMIC ELECTRICAL CHARACTERISTICS

 $(V_{BIAS} (V_{DD}, V_{BS}) = 15.0 \text{ V}, \text{ V}_{S} = \text{V}_{SS} = \text{COM} = 0 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}, \text{ C}_{LOAD} = 1000 \text{ pF} \text{ unless otherwise specified})$ 

Symbol	Characteristic	Condition	Min.	Тур.	Max.	Unit
t <sub>on</sub>	Turn-on Propagation Delay	V <sub>S</sub> = 0 V		140	200	ns
t <sub>off</sub>	Turn-off Propagation Delay	V <sub>S</sub> = 0 V		140	200	ns
MT	Delay Matching				55	ns
t <sub>r</sub>	Turn-on Rise Time			25	50	ns
t <sub>f</sub>	Turn-off Fall Time			25	50	ns

### **Typical Characteristics**







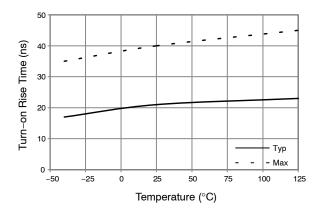


Figure 8. Turn-on Rise Time vs. Temperature

60

50

40

30

20

10

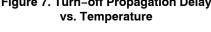
0

-50

-25

0

Delay Matching of turn on (ns)



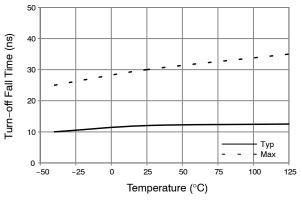


Figure 9. Turn-off Fall Time vs. Temperature

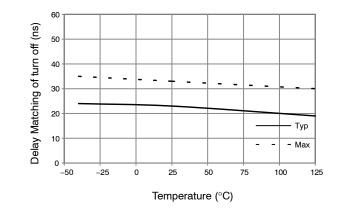


Figure 10. Turn-on Delay Matching vs. Temperature

Temperature (°C)

50

25

Figure 11. Turn-off Delay Matching vs. Temperature

Тур

125

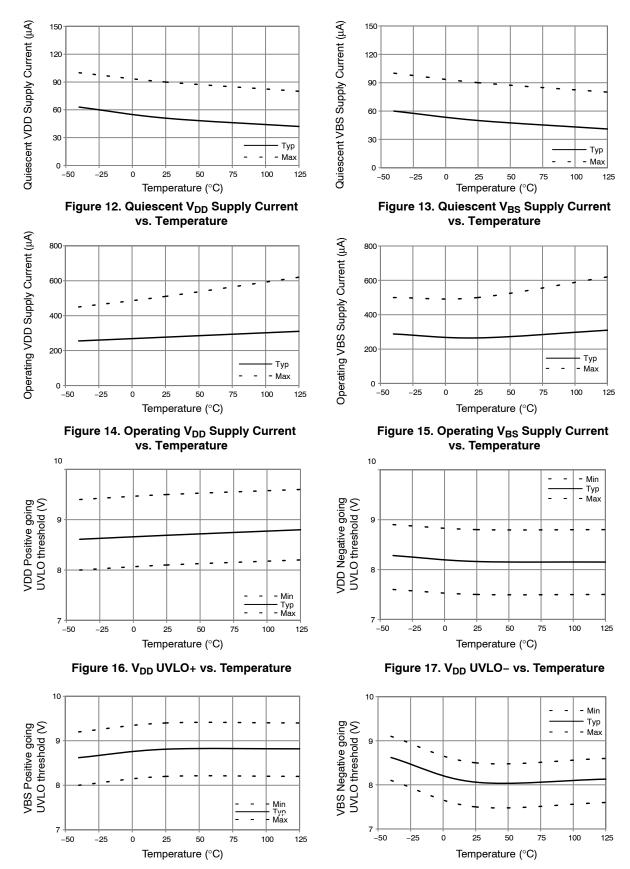
- Max

100

-

75

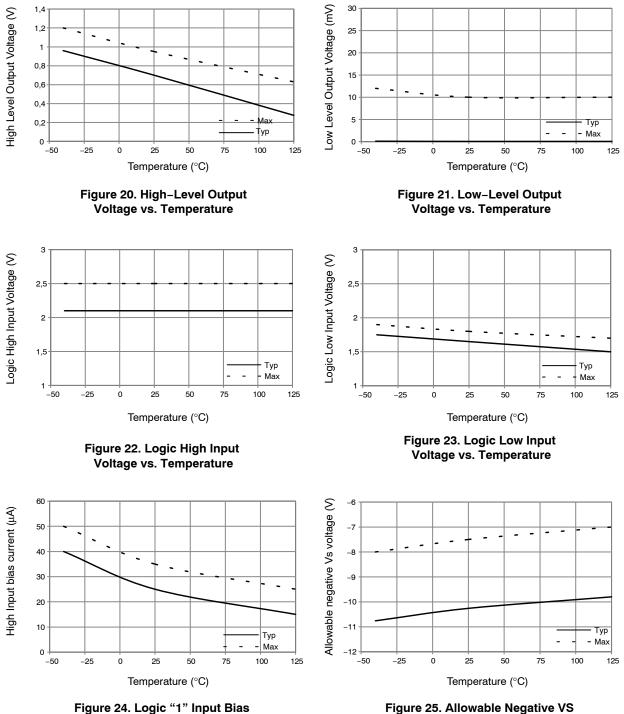
#### Typical Characteristics (continued)

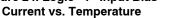


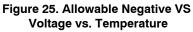




#### Typical Characteristics (continued)







#### **Switching Time Definitions**

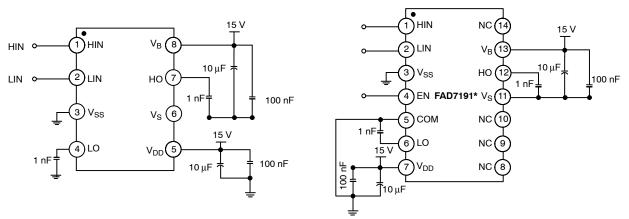


Figure 26. Switching Time Test Circuit

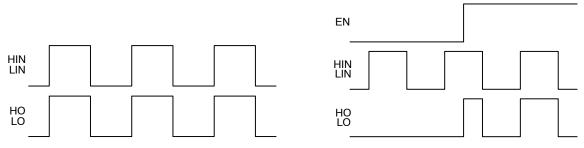


Figure 27. Input / Output Timing Diagram

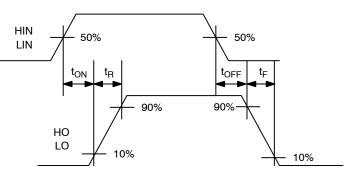
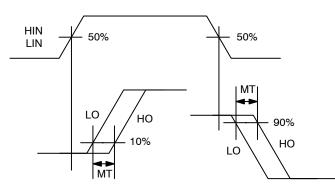
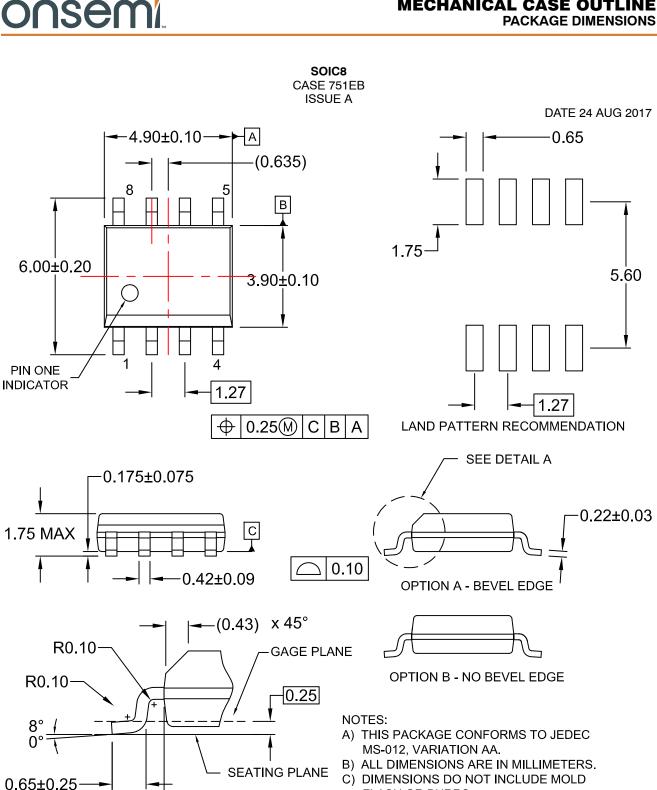


Figure 28. Switching Time Waveform Definitions





# **MECHANICAL CASE OUTLINE**



C) DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS. D) LANDPATTERN STANDARD: SOIC127P600X175-8M

DOCUMENT NUMBER:	98AON13735G Electronic versions are uncontrolled except when accessed directly from the Document Report Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.				
DESCRIPTION:	SOIC8		PAGE 1 OF 1		

(1.04)

DETAIL À SCALE 21

onsemi and OnSemi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make charges without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products herein. special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

5.60

0.22±0.03

# onsemi

SOIC14 CASE 751EF **ISSUE O** DATE 30 SEP 2016 8.75 Α 8.50 0.65 7.62 14 8 14 8 В ₽ ╞ 4.00 6.00 5.60 3.80 Ħ = ╞ = Ħ 1.70 7 **PIN #1** 7 1.27 1 0.51 IDENT. 1.270.35 (0.33) - $\oplus$  0.25 (M) С В Α LAND PATTERN RECOMMENDATION TOP VIEW 1.75 MAX 0.25 0.19 0.10 С 1.50 0.25 1.25 0.10 SIDE VIEW FRONT VIEW NOTES: A. CONFORMS TO JEDEC MS-012, VARIATION AB, ISSUE C **B. ALL DIMENSIONS ARE IN MILLIMETERS** 0.50 0.25 × 45° C. DIMENSIONS DO NOT INCLUDE MOLD FLASH OR BURRS R0.10 GAGE D. LAND PATTERN STANDARD: PLANE SOIC127P600X145-14M E. CONFORMS TO ASME Y14.5M, 2009 R0.10 0.36 8° 0° 0.90 0.50 SEATING PLANE (1.04)**DETAIL A** SCALE 16:1

DOCUMENT NUMBER:	98AON13739G	Electronic versions are uncontrolled except when accessed directly from the Document Repositor Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.		
DESCRIPTION:	SOIC14	-	PAGE 1 OF 1	

onsemi and ONSEMi are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.

onsemi, ONSEMI, and other names, marks, and brands are registered and/or common law trademarks of Semiconductor Components Industries, LLC dba "onsemi" or its affiliates and/or subsidiaries in the United States and/or other countries. onsemi owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of onsemi's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent\_Marking.pdf</u>. onsemi reserves the right to make changes at any time to any products or information herein, without notice. The information herein is provided "as-is" and onsemi makes no warranty, representation or guarantee regarding the accuracy of the information, product features, availability, functionality, or suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or indental damages. Buyer is responsible for its products and applications using onsemi products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by onsemi. "Typical" parameters which may be provided in onsemi data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. onsemi does not convey any license under any of its intellectual property rights nor the rights of others. onsemi products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification. Buyer shall indemnify and hold onsemi and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs,

#### ADDITIONAL INFORMATION

TECHNICAL PUBLICATIONS:

Technical Library: www.onsemi.com/design/resources/technical-documentation onsemi Website: www.onsemi.com

ONLINE SUPPORT: <u>www.onsemi.com/support</u> For additional information, please contact your local Sales Representative at <u>www.onsemi.com/support/sales</u>

# **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

onsemi:

FAN7191MX-F085 FAD7191M1X